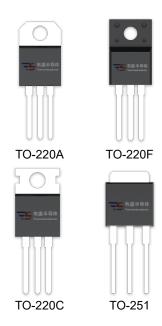


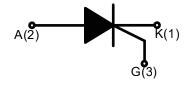
### **DESCRIPTION:**

With high ability to withstand the shock loading of large current, TN1215-800H series of silicon controlled rectifiers provide high dv/dt rate with strong resistance to electromagnetic interference. They are especially recommended for use on solid state relay, motorcycle, power charger, T-tools etc.



### **MAIN FEATURES**

Symbol	Value	Symbol
V <sub>DRM</sub> / V <sub>RRM</sub>	650/800	V
I <sub>T(RMS)</sub>	12	Α
I <sub>GT</sub>	≤15	mA



### **ABSOLUTE MAXIMUM RATINGS**

Parameter		Symbol	Value	Unit
Storage junction temperature range		T <sub>stg</sub>	-40 - 150	${\mathbb C}$
Operating junction temperature range		Tj	-40 - 150	$^{\circ}$
Repetitive peak off-state voltage (T <sub>j</sub> =25°ℂ)		$V_{DRM}$	650/800	V
Repetitive peak reverse voltage (T <sub>j</sub> =25°C)		V <sub>RRM</sub>	650/800	V
RMS on-state current	TO-251/ TO-220C/ TO-220A (Non-Ins) (T <sub>C</sub> =130℃) TO-220A (Ins)/ TO-220F (Ins) (T <sub>C</sub> =125℃)	I <sub>T(RMS)</sub>	12	А
Non repetitive surge peak on-state current (F=50Hz tp=10ms)		Ітѕм	120	А



Non repetitive surge peak on-state current (F=60Hz tp=8.3ms)	I <sub>TSM</sub>	132	А
I <sup>2</sup> t value for fusing (tp=10ms)	l <sup>2</sup> t	72	A <sup>2</sup> s
Repetitive rate of rise of on-state current $(I_G=2\times I_{GT})$	dl⊤/dt	50	A/µs
Peak gate current	I <sub>GM</sub>	2	Α
Peak gate power	P <sub>GM</sub>	5	W
Average gate power dissipation	P <sub>G(AV)</sub>	0.5	W

# **ELECTRICAL CHARACTERISTICS** (T<sub>j</sub>=25°C unless otherwise specified)

Symbol	Test Condition	Value			Unit
Symbol	rest Condition	MIN.	TYP.	MAX.	Unit
I <sub>GT</sub>	$V_D=12V R_L=33\Omega$	-	4	15	mA
V <sub>GT</sub>	VD-12V KL-3312	-	0.75	1.5	V
V <sub>GD</sub>	$V_D=V_{DRM}T_j=150^{\circ}C$ RL=3.3K $\Omega$	0.2	-	-	V
IL	I <sub>G</sub> =1.2I <sub>GT</sub>	-	12	40	mA
lн	I⊤=500mA	-	12	30	mA
dV/dt	V <sub>D</sub> =540V Gate Open T <sub>j</sub> =150℃	50	-	-	V/µs
dV/dt	V <sub>D</sub> =436V Gate Open T <sub>j</sub> =150℃	80	-	-	V/µs
ton	I <sub>GT</sub> =20mA I <sub>A</sub> =100mA I <sub>R</sub> =10mA	-	2	-	μs
t <sub>off</sub>	T <sub>j</sub> =25℃	-	30	-	μs
R <sub>d</sub>	Dynamic resistance T <sub>j</sub> =125℃	-	-	35	mΩ

### **STATIC CHARACTERISTICS**

Symbol	Parameter		Value(MAX)	Unit
V <sub>TM</sub>	I <sub>TM</sub> =23A tp=380μs	T <sub>j</sub> =25℃	1.6	V
IDRM	V <sub>D</sub> =V <sub>DRM</sub> V <sub>R</sub> =V <sub>RRM</sub>	Tj=25℃	10	μA
IRRM		Tj=150℃	1	mA



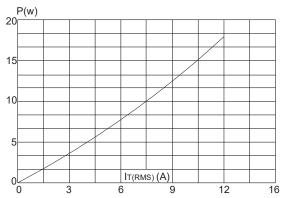
Shenzhen VSEEI Semiconductor Co., Ltd

## **THERMAL RESISTANCES**

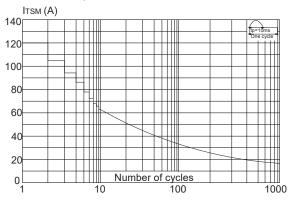
Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	Junction to case	TO-251/ TO-220C/ TO-220A (Non-Ins)	1.3	· °C/W
		TO-220A (Ins)	1.6	C/VV
		TO-220F (Ins)	1.7	



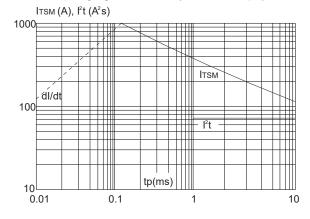
**FIG.1:** Maximum power dissipation versus RMS on-state current



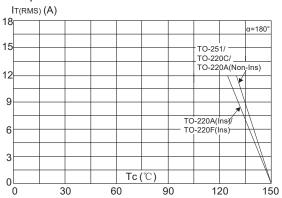
**FIG.3:** Surge peak on-state current versus number of cycles



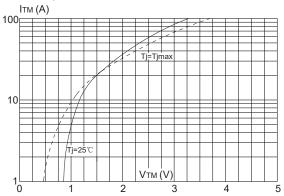
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<10ms, and corresponging value of I²t (dI/dt < 50A/μs)



**FIG.2:** RMS on-state current versus case temperature



**FIG.4:** On-state characteristics (maximum values)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature

